NC263UR

Solder plus Support

HALOGEN FREE

No Clean Liquid Flux

Features:

- Rosin and Resin-Free
- Increased Activity Level
- Can be Sprayed, Foamed Dipped or Misted
- Broad Process Window
- Halide-Free

Description:

NC263UR is a rosin-free, resin-free, halide-free, no-clean wave solder flux designed to promote enhanced wetting during the wave soldering process. NC263UR has a higher activity level and lower surface tension than other no-clean liquid fluxes. NC263UR performs well with bare copper, solder-coated, and organic coated PWBs, leaving negligible post-process residues that are non-conductive and do not require post- process cleaning for most applications. NC263UR has a unique chemistry and wide process window, which makes it a drop-in for your wave soldering process.

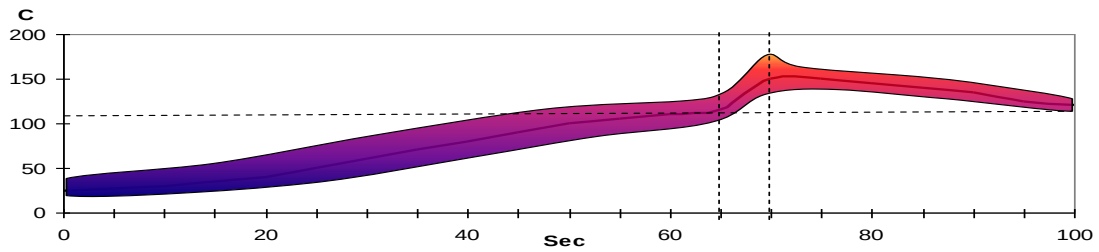
Flux Application:

- NC263UR is formulated for application via spray, foam, brush, mist, or dip. For spraying, NC263UR is ready to use directly from its container, no thinning required. When spray fluxing, it is imperative that proper flux coverage and uniformity be achieved and maintained. A dry flux coating of 500-1500 micrograms per square inch is recommended as a starting point.
- When nitrogen sealed wave solder equipment is used, it is generally necessary to apply slightly more flux than normal as a result of excess drying due to the extended length of the equipment.
- When foaming, air stones should be supplied with compressed air, free of oil and moisture. Adjust foam head to achieve uniform bubble size for optimum coverage. During foaming applications, it is periodically necessary to add AIM's Common Flux Thinner to replace that which is lost due through evaporation.

Process Control:

Because of the low percentage of solids in this flux, control of specific gravity with automated equipment usually is found to be ineffective; therefore, control via titration is necessary. AIM's Titration Kit has proven to be cost-effective, user friendly, quick and accurate. Titration should be carried out at least once an hour for flux foaming operations, or more often if large variances are found.

Thermal Profile:



RATE of RISE	PROGRESS THROUGH	PCB TOP SIDE TEMP	COOLDOWN
2-3ºC / SEC MAX	66°C - 77°C (150 - 170ºF)	87°C - 115°C (190ºF - 240ºF)	≤ 4ºC
	≤ 40 SECONDS	JUST BEFORE WAVE	

Cleaning:

NC263UR can be cleaned, if necessary, with saponified water or an appropriate solvent cleaner. Please refer to the AIM No-Clean-Cleaner Matrix for a list of suitable cleaning materials.

Handling:

- NC263UR has an unopened shelf life of 1 year when stored at room temperature.
- Do not store near fire or flame. Keep away from sunlight as it may degrade product.
- NC263UR is shipped ready-to-use, no mixing necessary.
- Do not mix used and unused chemical in the same container. Reseal any opened containers.

Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **M**aterial **S**afety **D**ata **S**heet for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

Physical Properties:

Parameter	Value
J-STD-004	ORM0
Visual	Clear, Colorless
Odor	Aromatic (Slightly)
Solids Content	4.86%
Acid Number	16.14 mg KOH per gram flux

Parameter	Value
Specific Gravity	0.80 (water = 1)
Flash Point	< 10°C
Boiling Point	82°C
pH (1% solution /water)	4.88

Corrosion Testing:

Parameter	Requirements	Results
Copper Mirror (24 hrs @ 25°C, 50%RH)	IPC-TM-650-2.3.32	Med
Halide Test (Silver Chromate)	IPC-TM-650-2.2.33	Pass

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AIM IS ISO9001:2008 & ISO14001:2004 CERTIFIED

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